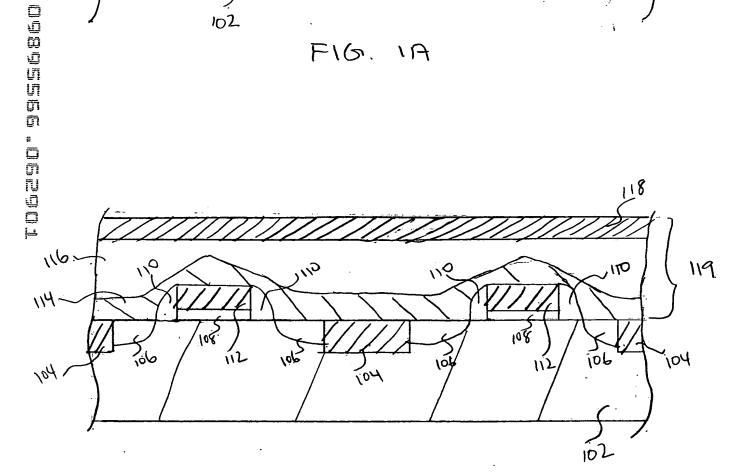
FIG. 17



F16. 1B

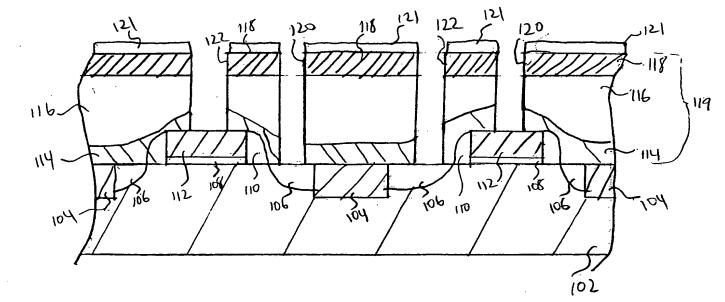
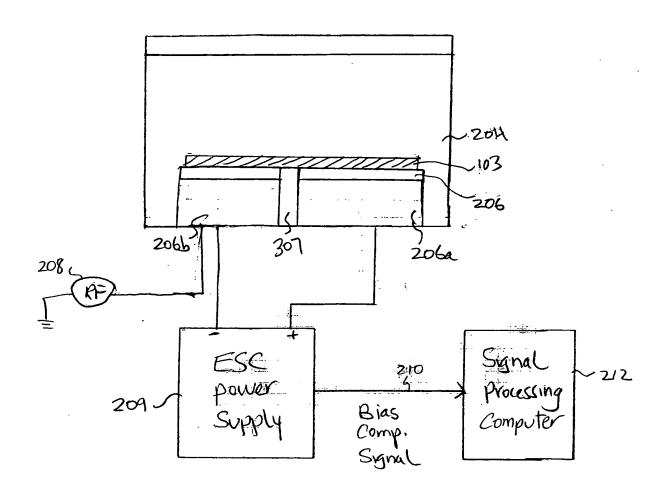
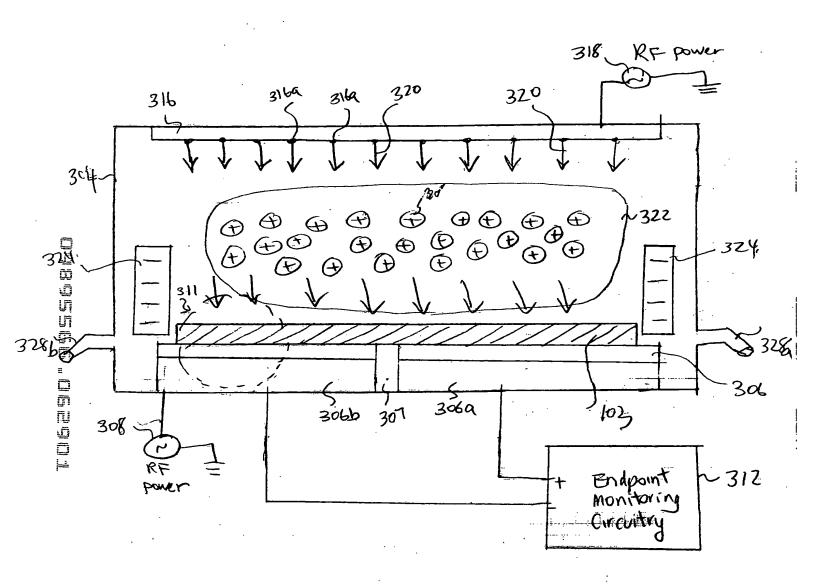


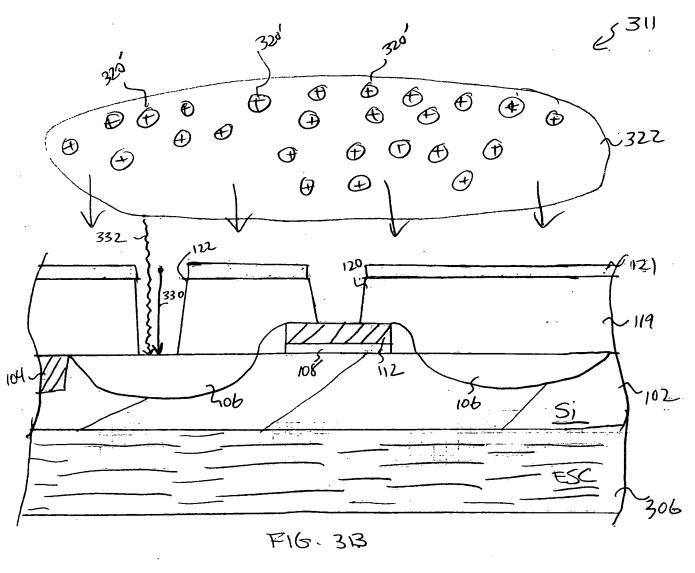
FIG IC

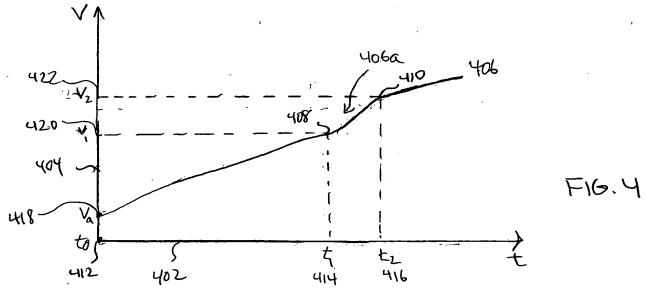


F16. 2



F16.3A

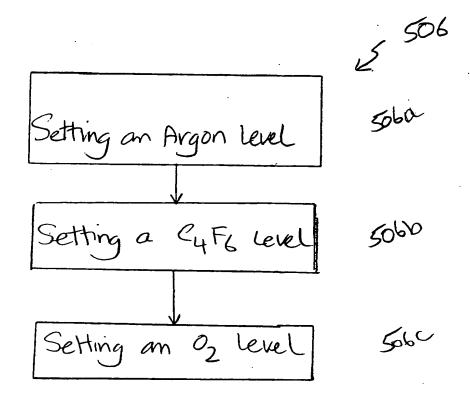




£ 500 Start Provide a Subtrate having 502 an ILD layer to be etched Inserting substrate into 504 a chamber In troducing etchant gases 506 Powering up the Chamber to strike a plasma to 508 commence etching Monitoring a substrate 50 bias level Discontinue the etching 512 when a target bias compensation Level is reached Removing substrate from chamber and prepare for additional processing it 514 disired

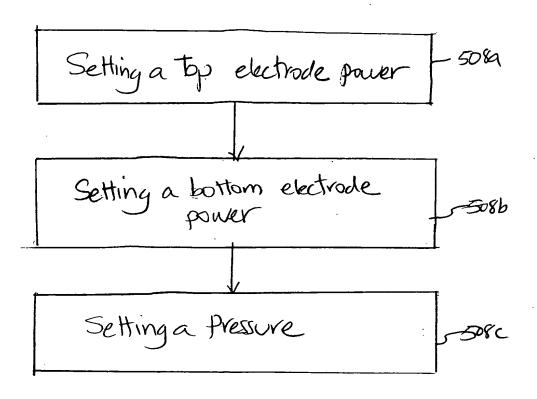
Done

F16.5A



F161.513





F16.5C